



Spec No.: DS70-2001-027 Effective Date: 11/30/2016

Revision: E

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4



1. **DESCRIPTION**

1.1 Features

- Isolation voltage between input and output V_{iso}: 5,000V_{rms}
- 6pin DIP zero-cross optoisolators triac driver output
- High repetitive peak off-state voltage VDRM : Min. 800V
- High critical rate of rise of off-state voltage(dV/dt : MIN. 1000V / μs)
- Dual-in-line package: MOC3081 / MOC3082 / MOC3083
- Wide lead spacing package: MOC3081M / MOC3082M / MOC3083M
- Surface mounting package: MOC3081S / MOC3082S / MOC3083S
- Tape and reel packaging: MOC3081S-TA1 / MOC3082S-TA1 / MOC3083S-TA1
- Safety approval

UL 1577

cUL CA5A

VDE DIN EN60747-5-5 (VDE 0884-5)

- RoHS Compliance
 - All materials be used in device are followed EU RoHS directive (No.2002/95/EC).
- MSL class1

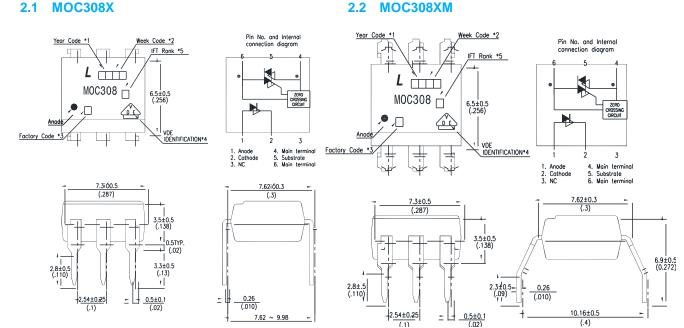
1.2 Applications

- AC Motor Drives
- AC Motor Starters
- E.M. Contactors
- Lighting Controls
- Solenoid/Valve Controls
- Solid State Relays
- Static Power Switches
- Temperature Controls

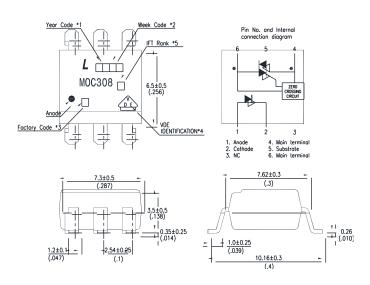


2. PACKAGE DIMENSIONS

MOC308X



2.3 MOC308XS



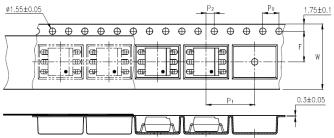
Notes:

- 1. Year date code.
- 2. 2-digit work week.
- 3. Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. VDE option
- 5. I_{FT} rank
- * Dimensions are in Millimeters and (Inches).

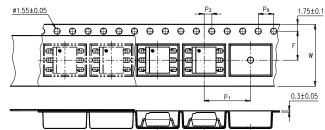


3. TAPING DIMENSIONS

3.1 MOC308XS-TA



3.2 MOC308XS-TA1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P ₀	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P ₂	2±0.1 (0.079)
Distance of compartment to compartment	P ₁	12±0.1 (0.472)

3.3 Quantities Per Reel

Package Type	MOC308XS series				
Quantities (pcs)	1000				



4. RATING AND CHARACTERISTICS

4.1 Absolute Maximum Ratings at Ta=25°C

	Parameter	Symbol	Rating	Unit
	Forward Current	I _F	50	mA
To a f	Reverse Voltage	V_{R}	6	V
Input	Junction Temperature	T_J	125	°C
	Power Dissipation	Р	120	mW
	Off-State Output Terminal Voltage	V_{DRM}	800	V
Output	On-State RMS Current	I _{D(RMS)}	100	mA
	Peak Repetitive Surge Current (PW=1ms, 120pps)	I _{TSM}	1	А
	Junction Temperature	Τ _J	125	°C
	Collector Power Dissipation	Pc	150	mW
	Total Power Dissipation	P _{tot}	250	mW
1.	Isolation Voltage	$V_{\rm iso}$	5000	V_{rms}
	Operating Temperature	T_{opr}	-40 ~ +110	°C
	Storage Temperature	T_{stg}	-55 ~ +150	°C
2.	Soldering Temperature	T_{sol}	260	°C

1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.
- 2. For 10 Seconds



4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

Parameter		Symb	Min.	Тур.	Max.	Unit	Test Condition		
1	Forward Voltage		V _F	_	1.2	1.4	٧	I _F =20mA	
Input		Reverse Current		I _R	_	0.05	10	μА	V _R =6V
Peak Blocking Current, Either 1 Direction		I _{DRM}	_	_	500	nA	V _{DRM} = 800V		
Output	Peak On-State Voltage, Either Direction		V_{TM}	_	_	3.0	V	I _{TM} =100 mA Peak	
	Critical rate of Rise of Off-State 2 Voltage		dv/dt	1000	_	_	V/μs	Vin=240Vrms	
Couple	Led Trigger Current, Current Required to 3 Latch Output, Either Direction	MOC3081	I _{FT}	_	_	15	mA	Main Terminal Voltage = 3V	
		MOC3082		_	_	10			
		MOC3083		_	_	5			
	Holding Current, Either Direction		l _Η	_	400	_	μА		
ZERO CROSSING		Inhibit Voltage		V _{INH}	_	5	20	Volts	I _F =Rated I _{FT} , MT1-MT2 Voltage above which device will not trigger.
3.100010	Leakage in Inhibited State		I _{DRM2}	_	_	500	μА	I_F = Rated I_{FT} , Rated V_{DRM} , Off State	

^{*1.} Test voltage must be applied within dv/dt rating.

^{*2.} This is static dv/dt. Commutating dv/dt is a function of the load-driving thyristor(s) only.

^{*3.} All devices are guaranteed to trigger at an I_F value less than or equal to max I_{FT}. Therefore, recommended operating I_F lies between max I_{FT}, 15 mA for MOC3081, 10 mA for MOC3082, 5 mA for MOC3083, and absolute max I_F (50mA).



5. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward Current vs.

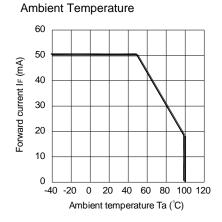


Fig.3 Minimum Trigger Current vs. Ambient Temperature

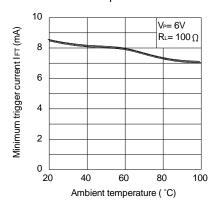


Fig.5 On-state Voltage vs. Ambient Temperature

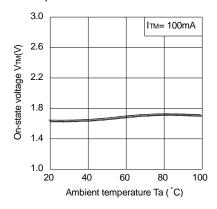


Fig.2 On-state Current vs. Ambient Temperature

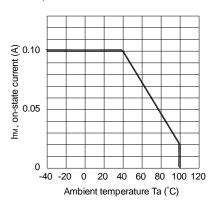


Fig.4 Forward Current vs. Forward Voltage

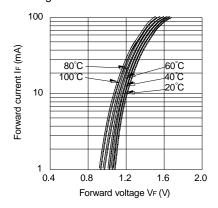


Fig.6 Holding Current vs.

Ambient Temperature

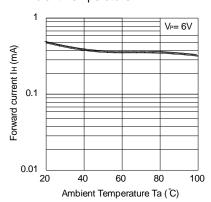




Fig. 7 Repetitive Peak Off-state Current vs. Temperature

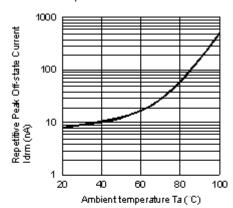
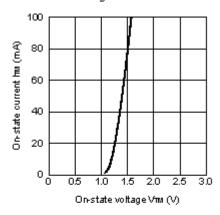
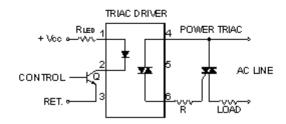


Fig. 8 On-state Current vs.

On-state Voltage



Basic Driver Circuit



Rues=(Voo-Vr LED-VsaQ)/ Irm R= Vp AC line/Iran

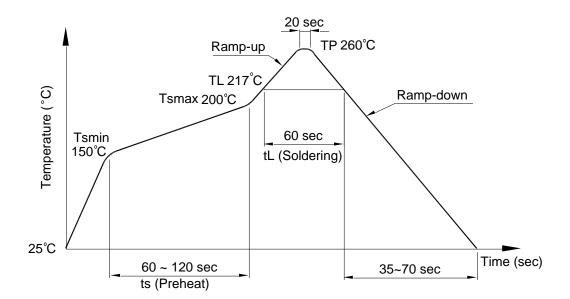


6. TEMPERATURE PROFILE OF SOLDERING

6.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three

Profile item	Conditions			
Preheat				
- Temperature Min (T _{Smin})	150°C			
- Temperature Max (T _{Smax})	200°C			
- Time (min to max) (ts)	90±30 sec			
Soldering zone				
- Temperature (T _L)	217°C			
- Time (t _L)	60 sec			
Peak Temperature (T _P)	260°C			
Ramp-up rate	3°C / sec max.			
Ramp-down rate	3~6°C / sec			







6.2 Wave soldering (JEDEC22A111 compliant)

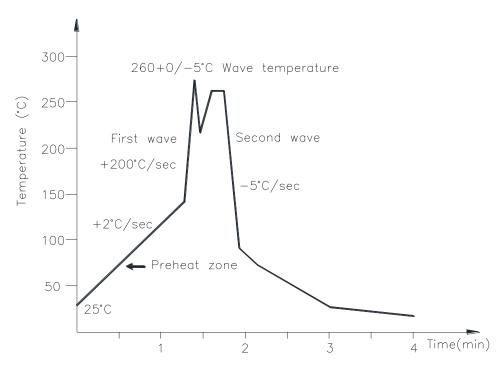
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



6.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5°C

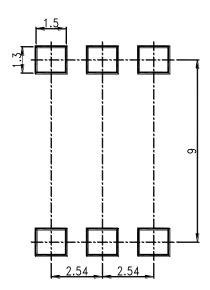
Time: 3 sec max.





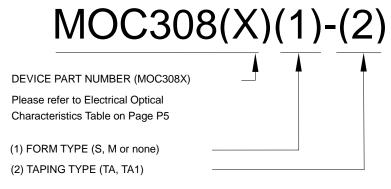
7. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

Unit: mm

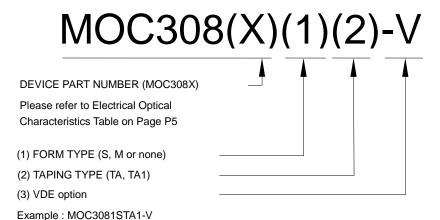




8. NAMING RULE



Example : MOC3081S-TA1



9. NOTES

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.